

DESCRIPTION

The CNX48U, H11BX, MOC8080 and TIL113 have a gallium arsenide infrared emitter optically coupled to a silicon planar photodarlington.

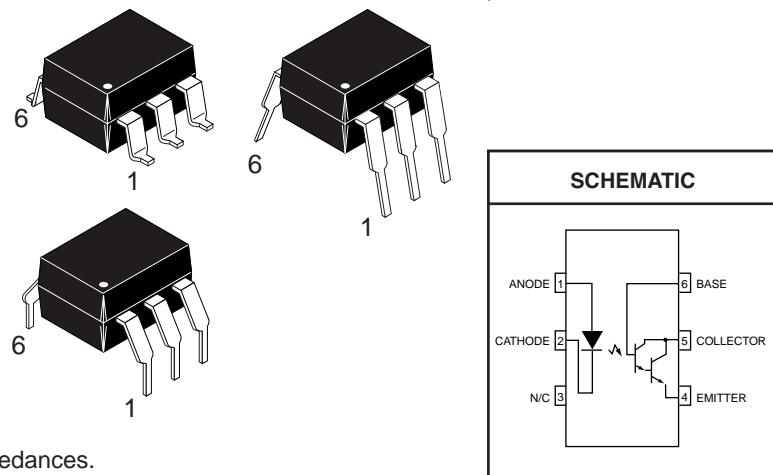
| | | | | |
|---------|--------|-------|---------|-------|
| CNX48U | H11B1 | H11B2 | H11B255 | H11B3 |
| MOC8080 | TIL113 | | | |

FEATURES

- High sensitivity to low input drive current
- Meets or exceeds all JEDEC Registered Specifications
- VDE 0884 approval available as a test option
-add option .300. (e.g., H11B1.300)

APPLICATIONS

- Low power logic circuits
- Telecommunications equipment
- Portable electronics
- Solid state relays
- Interfacing coupling systems of different potentials and impedances.



| Parameter | Symbol | Device | Value | Units |
|--|------------------|---|----------------|-------------|
| TOTAL DEVICE | | | | |
| Storage Temperature | T_{STG} | All | -55 to +150 | °C |
| Operating Temperature | T_{OPR} | All | -55 to +100 | °C |
| Lead Solder Temperature | T_{SOL} | All | 260 for 10 sec | °C |
| Total Device Power Dissipation @ $T_A = 25^\circ\text{C}$ | P_D | All | 250 | mW |
| Derate above 25°C | | | 3.3 | mW/°C |
| EMITTER | | | | |
| Continuous Forward Current | I_F | All | 100 | mA |
| Reverse Voltage | V_R | All | 6 | V |
| Forward Current - Peak (300 μs , 2% Duty Cycle) | $I_F(\text{pk})$ | All | 3.0 | A |
| LED Power Dissipation @ $T_A = 25^\circ\text{C}$ | P_D | All | 100 | mW |
| Derate above 25°C | | | 1.8 | mW/°C |
| DETECTOR | | | | |
| Collector-Emitter Breakdown Voltage | BV_{CEO} | CNX48U, TIL113 H11B1, H11B2 H11B3 H11B255 MOC8080 | 30 25 55 | V |
| Collector-Base Breakdown Voltage | BV_{CBO} | CNX48U, H11B1 H11B2, H11B3 TIL113 H11B255 MOC8080 | 30 55 | V |
| Emitter-Collector Breakdown Voltage | BV_{ECO} | All | 7 | V |
| Detector Power Dissipation @ $T_A = 25^\circ\text{C}$ | P_D | All | 150 2.0 | mW mW/°C |
| Derate above 25°C | | | | |

| | | | | |
|---------|--------|-------|---------|-------|
| CNX48U | H11B1 | H11B2 | H11B255 | H11B3 |
| MOC8080 | TIL113 | | | |

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ Unless otherwise specified.)

INDIVIDUAL COMPONENT CHARACTERISTICS

| Parameter | Test Conditions | Symbol | Device | Min | Typ** | Max | Unit |
|--|--|------------|---------------|-----|-------|-----|---------------|
| EMITTER | ($I_F = 10 \text{ mA}$) | V_F | H11B1, H11B2 | 0.8 | 1.2 | 1.5 | V |
| | ($I_F = 10 \text{ mA}$) | | H11B255 | | | | |
| | ($I_F = 10 \text{ mA}, T_A = -55^\circ\text{C}$) | | MOC8080 | | | | |
| | ($I_F = 10 \text{ mA}, T_A = 100^\circ\text{C}$) | | TIL113 | | | | |
| | ($I_F = 50 \text{ mA}$) | | CNX48U | | | | |
| Reverse Leakage Current | ($V_R = 6 \text{ V}$) | I_R | All | | 0.001 | 10 | μA |
| Capacitance | ($V_F = 0 \text{ V}, f = 1.0 \text{ MHz}$) | C | All | | 50 | | pF |
| DETECTOR | ($I_C = 1 \text{ mA}, I_F = 0$) | BV_{CEO} | CNX48U | 30 | 60 | | V |
| | ($I_C = 100 \mu\text{A}, I_F = 0$) | | TIL113 | | | | |
| | ($I_C = 10 \text{ mA}, I_F = 0$) | | H11B1, H11B2 | 25 | 60 | | |
| | ($I_C = 100 \mu\text{A}, I_F = 0$) | | H11B3 | | | | |
| | ($I_C = 1 \text{ mA}, I_F = 0$) | | H11B255 | 55 | 70 | | |
| Collector-Base Breakdown Voltage | ($I_C = 100 \mu\text{A}, I_E = 0$) | BV_{CBO} | MOC8080 | | | | V |
| | ($I_C = 100 \mu\text{A}, I_F = 0$) | | CNX48U, H11B1 | 30 | 100 | | |
| | | | H11B2, H11B3 | | | | |
| Emitter-Collector Breakdown Voltage | ($I_C = 100 \mu\text{A}, I_E = 0$) | BV_{ECO} | TIL113 | | | | V |
| | ($I_C = 100 \mu\text{A}, I_F = 0$) | | H11B255 | 55 | 100 | | |
| Collector-Emitter Dark Current | ($V_{CE} = 10 \text{ V}, \text{Base Open}$) | I_{CEO} | MOC8080 | All | 7 | 10 | V |

Note

** Typical values at $T_A = 25^\circ\text{C}$

| | | | | |
|---------|--------|-------|---------|-------|
| CNX48U | H11B1 | H11B2 | H11B255 | H11B3 |
| MOC8080 | TIL113 | | | |

TRANSFER CHARACTERISTICS ($T_A = 25^\circ\text{C}$ Unless otherwise specified.)

| DC Characteristics | Test Conditions | Symbol | Device | Min | Typ** | Max | Units |
|---|--|----------------------|----------------|------------|-------|------|---------------|
| Collector Output Current ⁽¹⁾ | ($I_F = 10 \text{ mA}$, $V_{CE} = 5 \text{ V}$) | I_C (CTR) | MOC8080 | 50 (500) | | | mA (%) |
| | ($I_F = 10 \text{ mA}$, $V_{CE} = 1 \text{ V}$) | | H11B255 | 10 (100) | | | |
| | ($I_F = 1 \text{ mA}$, $V_{CE} = 5 \text{ V}$) | | CNX48U | 60 (600) | | | |
| | ($I_F = 1 \text{ mA}$, $V_{CE} = 1 \text{ V}$) | | TIL113 | 30 (300) | | | |
| | ($I_F = 0.5 \text{ mA}$, $V_{CE} = 1 \text{ V}$) | | H11B1 | 5 (500) | | | |
| | | | H11B2 | 2 (200) | | | |
| | | | H11B3 | 1 (100) | | | |
| | | | CNX48U | 5 (500) | | | |
| | | | | 1.75 (350) | | | |
| Saturation Voltage | ($I_F = 1 \text{ mA}$, $I_C = 1 \text{ mA}$) | $V_{CE(\text{sat})}$ | H11B1, H11B2 | | | 1.0 | V |
| | ($I_F = 5 \text{ mA}$, $I_C = 10 \text{ mA}$) | | H11B3, MOC8080 | | | 1.0 | |
| | ($I_F = 50 \text{ mA}$, $I_C = 50 \text{ mA}$) | | CNX48U | | | 1.0 | |
| | ($I_F = 8 \text{ mA}$, $I_C = 2 \text{ mA}$) | | H11B255 | | | 1.25 | |
| | | | TIL113 | | | | |
| AC Characteristics | $(I_C = 10 \text{ mA}, V_{CE} = 10 \text{ V})$ $(R_L = 100 \Omega)$ (Fig.7) | t_{on} | H11B1 | | 25 | | μs |
| | | t_{off} | H11B2 | | 18 | | |
| | $(I_F = 10 \text{ mA}, V_{CC} = 5 \text{ V})$ $(R_E = 100 \Omega)$, $(R_{BE} = 1M\Omega)$ (Fig. 8) | t_{on} | CNX48U | | 3.5 | | |
| | | t_{off} | | | 36 | | |
| | $(I_F = 1 \text{ mA}, V_{CC} = 5 \text{ V})$ $(R_E = 1k\Omega)$, $(R_{BE} = 10M\Omega)$ (Fig. 8) | t_{on} | | | 70 | | |
| | | t_{off} | | | 190 | | |
| | $(I_F = 5 \text{ mA}, V_{CC} = 10 \text{ V})$ $(R_L = 100 \Omega)$ (Fig.7) | t_{on} | MOC8080 | | 3.5 | | |
| | | t_{off} | | | 25 | | |
| | $(I_F = 200 \text{ mA}, I_C = 50 \text{ mA})$ $(V_{CC} = 10 \text{ V})$ ($R_L = 100 \Omega$) (Fig.7) | t_{on} | TIL113 | | 0.35 | 5 | |
| | | t_{off} | | | 55 | 100 | |

ISOLATION CHARACTERISTICS

| Characteristic | Test Conditions | Symbol | Min | Typ** | Max | Units |
|---|---|-----------|------|-----------|-----|-------------|
| Input-Output Isolation Voltage ⁽²⁾ | $(I_{I-O} \leq 1 \mu\text{A}, V_{rms}, t = 1 \text{ min.})$ | | 5300 | | | Vac(rms) |
| Isolation Resistance ⁽²⁾ | $(V_{I-O} = 500 \text{ VDC})$ | R_{ISO} | | 10^{11} | | Ω |
| Isolation Capacitance ⁽²⁾ | $(V_{I-O} = \emptyset, f = 1 \text{ MHz})$ | C_{ISO} | | 0.8 | | pf |

Note

** Typical values at $T_A = 25^\circ\text{C}$

| | | | | |
|---------|--------|-------|---------|-------|
| CNX48U | H11B1 | H11B2 | H11B255 | H11B3 |
| MOC8080 | TIL113 | | | |

Fig. 1 Output Current vs. Input Current

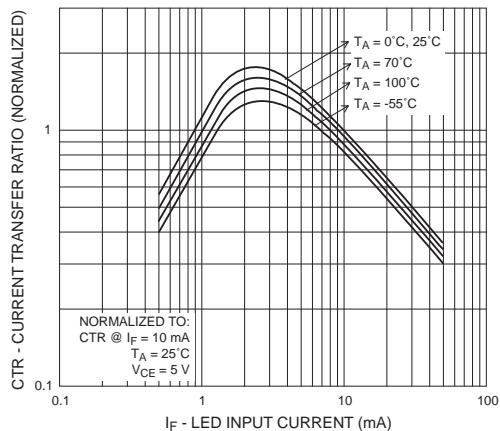


Fig. 2 Current Transfer Ratio vs. Ambient Temperature

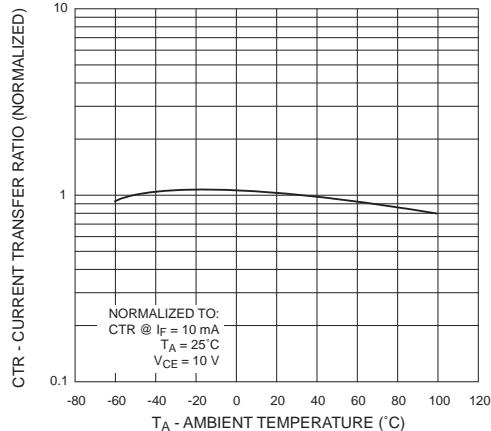


Fig. 3 Collector Current vs. Collector-Emitter Voltage

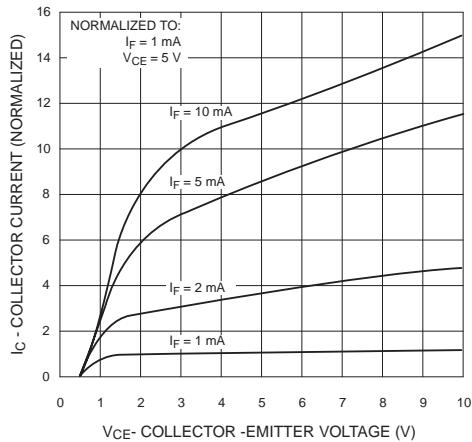


Fig. 4 Dark Current vs. Ambient Temperature

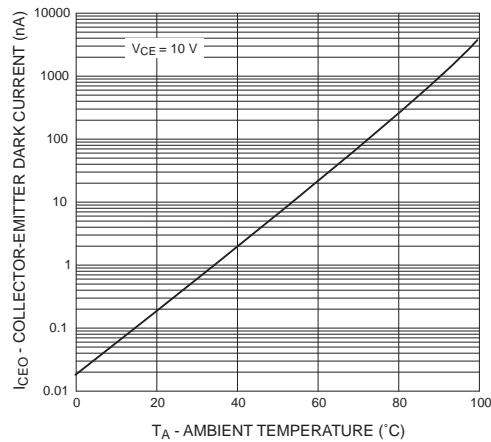


Fig. 5 Turn-On Time vs. Input Current

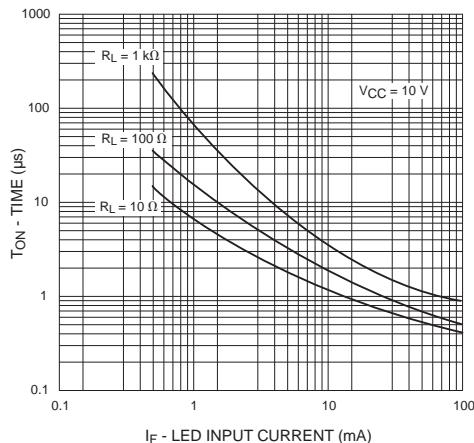
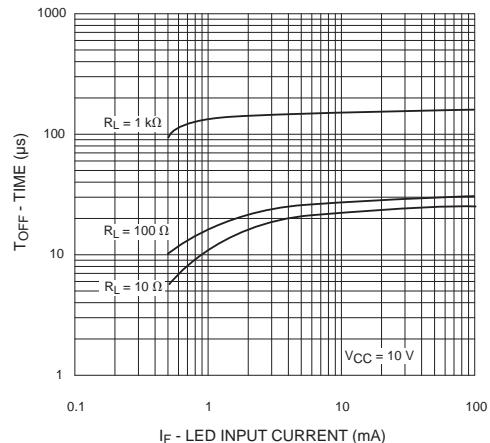


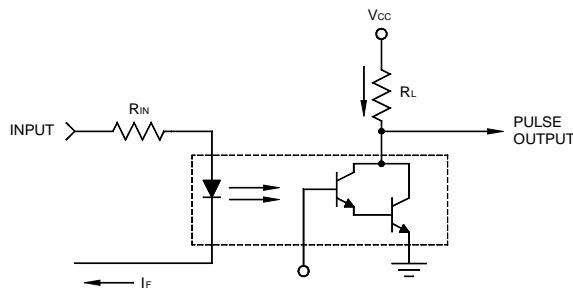
Fig. 6 Turn-Off Time vs. Input Current



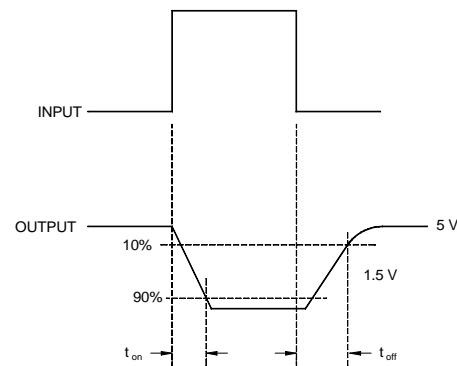
| | | | | |
|---------|--------|-------|---------|-------|
| CNX48U | H11B1 | H11B2 | H11B255 | H11B3 |
| MOC8080 | TIL113 | | | |

TYPICAL ELECTRO-OPTICAL CHARACTERISTIC CURVES

(25°C Free air temperature unless otherwise specified) (Cont.)

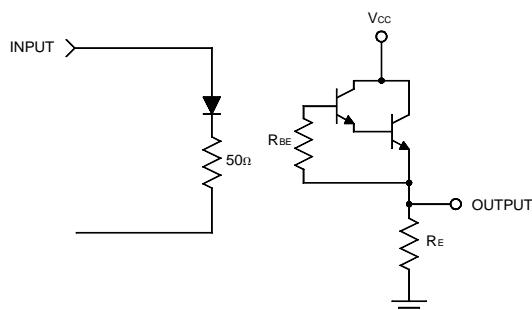


Test Circuit (All devices except CNX48U)

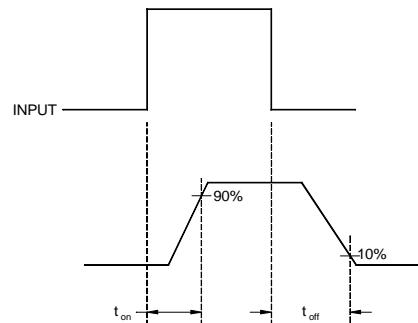


Switching Waveforms (All devices except CNX48U)

Fig. 7 Switching Time Test Circuit and Waveforms (All devices except CNX48U)



Test Circuit (CNX48U only)



Switching Waveforms (CNX48U only)

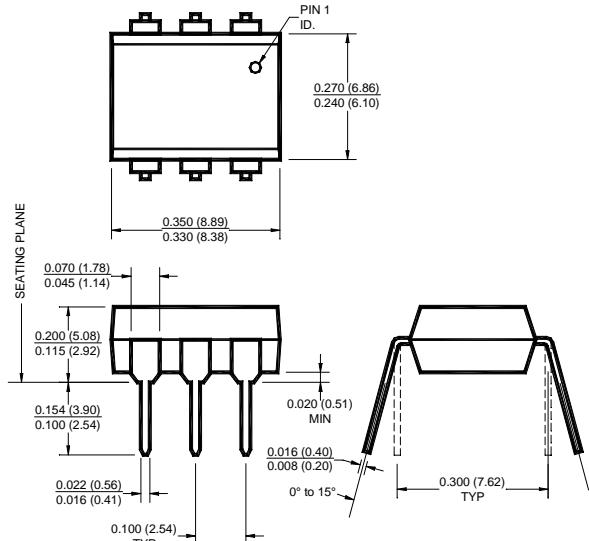
Fig. 8 Switching Time Test Circuit and Waveforms (CNX48U only)

Notes

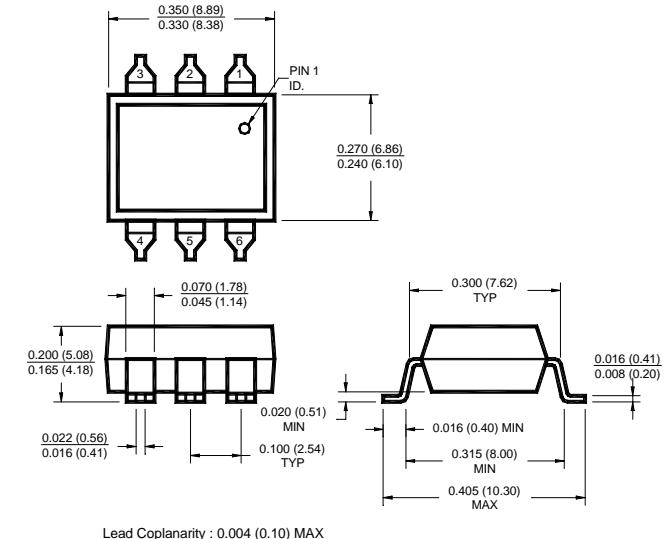
1. The current transfer ratio (I_C/I_F) is the ratio of the detector collector current to the LED input current with $V_{CE} @ 10\text{ V}$.
2. For this test, LED pins 1 and 2 are common and phototransistor pins 4,5 and 6 are common.

CNX48U H11B1 H11B2 H11B255 H11B3
MOC8080 TIL113

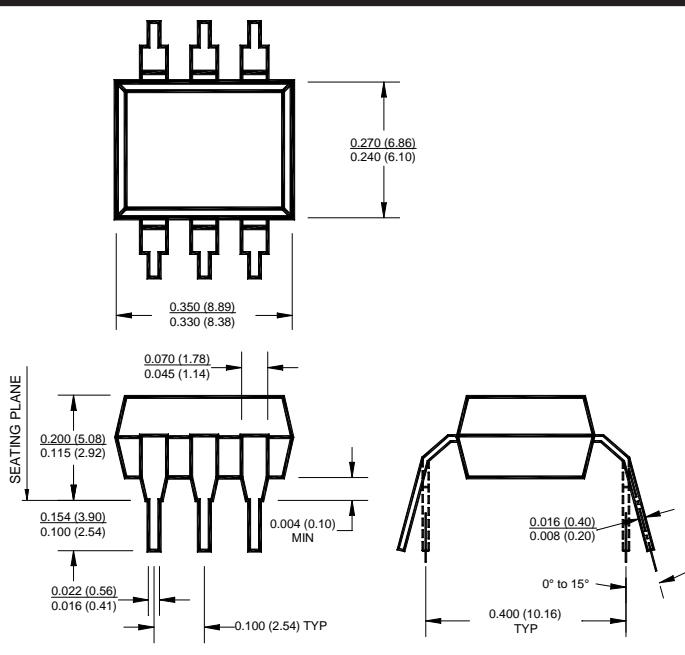
Package Dimensions (Through Hole)



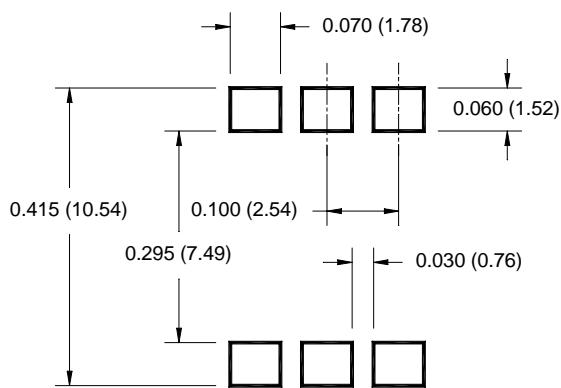
Package Dimensions (Surface Mount)



Package Dimensions (0.4"Lead Spacing)



Recommended Pad Layout for Surface Mount Leadform



NOTE

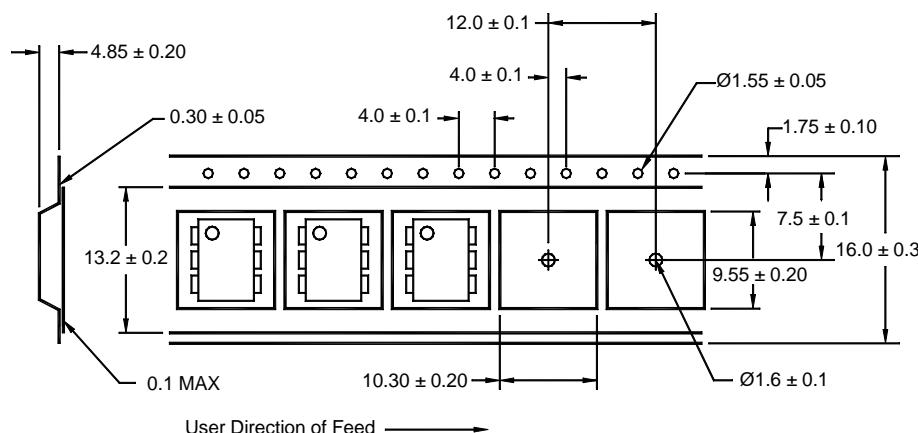
All dimensions are in inches (millimeters)

| | | | | |
|---------|--------|-------|---------|-------|
| CNX48U | H11B1 | H11B2 | H11B255 | H11B3 |
| MOC8080 | TIL113 | | | |

ORDERING INFORMATION

| Option | Order Entry Identifier | Description |
|--------|------------------------|--------------------------------------|
| S | .S | Surface Mount Lead Bend |
| SD | .SD | Surface Mount; Tape and reel |
| W | .W | 0.4" Lead Spacing |
| 300 | .300 | VDE 0884 |
| 300W | .300W | VDE 0884, 0.4" Lead Spacing |
| 3S | .3S | VDE 0884, Surface Mount |
| 3SD | .3SD | VDE 0884, Surface Mount, Tape & Reel |

QT Carrier Tape Specifications ("D" Taping Orientation)



NOTE

All dimensions are millimeters

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.